Abstracts

A New Chip Interconnection Technic for Ultra High-Speed and Millimeter-Wave Applications

G. Hanke and W.-D. Nohr. "A New Chip Interconnection Technic for Ultra High-Speed and Millimeter-Wave Applications." 1996 MTT-S International Microwave Symposium Digest 96.3 (1996 Vol. III [MWSYM]): 1611-1614.

Nearly lossless and non-reflecting interconnections between semiconductor-chips and transmission lines worhg up to 50 GHz can be realized in a "Reverse Beam-Lead Technic" as well as low-impedance ground and power supply interconnections. The paper describes the required technology, compares TDR and S-parameter measurements of state-of-the-art technics and the new one, and gives some examples of high-speed circuits.

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